

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SUI-HO TSAI	02/04/2021
CHENG-NENG CHEN	02/04/2021
YUN-NAN WANG	02/04/2021
CHIH-YUAN CHAO	02/04/2021
HSUEH-TSUNG LU	02/04/2021
RECEIVING PARTY DATA	
Name:	APLUS SEMICONDUCTOR TECHNOLOGIES CO., LTD.
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State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17181039
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NAME OF SUBMITTER:	KARIN L. WILLIAMS
SIGNATURE:	/Karin L. Williams/
DATE SIGNED:	02/22/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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ASSIGNMENT/DECLARATION FOR PATENT APPLICATION

WHEREAS, as a below named inventor, I hereby declare that:

My residence, mailing address, and citizenship are as stated below next to my name. I believe I am the original inventor (if only one name is listed below) or an original joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Double-sided and multilayer flexible printed circuit (FPC) substrate and method of processing the same

the specification of which is attached hereto.

The above application was made or authorized by me.

WHEREAS Aplus Semiconductor Technologies Co., Ltd. herein referred to as "Assignee" whose mailing address is No. 2288, Luheng Road, Economic Development Zone, Changzhou City, Jiangsu Province, China

is desirous of acquiring the entire right, title and interest in and to said invention, and in and to and under any and all Letters Patent to be obtained thereon.

NOW, THEREFORE, for and in consideration of one Dollar (\$1.00) and other good and valuable considerations, the receipt of which is hereby acknowledged, I/We the inventor(s) have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the Assignee, its successors and assigns the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all of my rights under International Convention, and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the Assignee in accordance herewith.

Upon said consideration, I/We do hereby covenant and agree with the said Assignee, its successors and assigns, that I/We will not execute any writing or do any act whatsoever conflicting with these presents, and that I/We or my/our executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

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